

Product Change Notification - RMES-20MUIN990

Date:

05 Jun 2020

Product Category:

USB Bridge; USB Hubs

Affected CPNs:**Notification subject:**

CCB 4199 Final Notice: Qualification of ASE as a new assembly site for USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-AC0 catalog part numbers (CPN) available in 64L QFN package.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-AC0 catalog part numbers (CPN) available in 64L QFN package.

Pre Change:

Assembled at STATS Chippac Ltd. (STA) site using gold (Au) bond wire, 8290 die attach and G700 molding compound material

Post Change:

Assembled at ASE Inc. (ASE) site using gold (CuPdAu) bond wire, EN4900F die attach and G631 molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	STATS Chippac Ltd. (STA)	ASE Inc. (ASE)
Wire material	Au	CuPdAu
Die attach material	8290	EN4900F
Molding compound material	G700	G631
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASE as a new assembly site.

Change Implementation Status:



In Progress

Estimated First Ship Date:

May 15, 2020 (date code: 2020)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2020					May 2020				
Workweek	14	15	16	17	18	19	20	21	22	23
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date							X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

April 21, 2020: Issued final notification. Attached is the qualification report and added the estimated first date by May 15, 2020.

June 05, 2020: Re-issued final notification to correct the package thickness information from 0.655mm to 0.9 mm in qualification report. Corrected the assembly site from STATS ChipPac (SCM) to STATS Chippac Ltd. (STA).

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-20MUIN990_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

USB2660I-JZX-03

USB2660I-JZX-03-TR

USB2517-JZX-AC0



MICROCHIP

QUALIFICATION REPORT SUMMARY

PCN #: RMES-20MUIN990

**Date:
April 2, 2020**

**Qualification of ASE as a new assembly site for
USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-
AC0 catalog part numbers (CPN) available in 64L QFN
package.**

Purpose: Qualification of ASE as a new assembly site for USB2660I-JZX-03, USB2660I-JZX-03-TR and USB2517-JZX-AC0 catalog part numbers (CPN) available in 64L QFN package.

CCB No.: 4199

Based on the available data, ASEK is qualified for the assembly of SMSC Production using the QFNE3C Package. Packages qualified are: 48QFNE3C, 56QFNE3C, 64QFNE3C and 72QFNE3C.

MANUFACTURING INFORMATION

PACKAGE TYPE	72 QFN (10X10X0.9 mm)
LEAD FRAME MATERIAL	C194
DIE ATTACH EPOXY TYPE	EN-4900F
WIRE TYPE	CuPdAu
MOLDING COMPOUND	G631

PACKAGE QUALIFICATION REPORT				
TEST ITEM	TEST CONDITION	TEST INTERVAL	VISUAL INSPECTION	TEST RESULTS
PRE-CONDITION TEST	JEDEC 22-A113 Level 3 30C/60%RH	192 HRS	0/240	0/240
TEMPERATURE CYCLE TEST	JEDEC 22-A104 -65°C~150°C	1000 Cycles	0/60	0/60
		1500 Cycles	0/60	0/60
HIGH TEMPERATURE STORAGE TEST	JEDEC 22-A103 150°C	1000 hours	0/60	0/60
		1500 hours	0/60	0/60
HAST	+130°C/85%RH, 96 hrs. Bias Volt: 1.2 V, 3.3 Volts	96 HRS	0/231	0/231
	+130°C/85%RH, 192 hrs. Bias Volt: 1.2 V, 3.3 Volts	192 HRS	0/231	0/231
HAST TEST (NO BIAS)	JEDEC 22-A118 130°C/85%RH 33.5PSIA	100 HRS	0/60	0/60
		150 HRS	0/60	0/60
TEMPERATURE HUMIDITY TEST (NO BIAS)	JEDEC 22-A101 85°C/85%RH	1000 hours	0/60	0/60
		1500 hours	0/60	0/60